

N-Channel MOSFET



Lead Free Package and Finish

Applications:

- Adaptor
- Charger
- SMPS

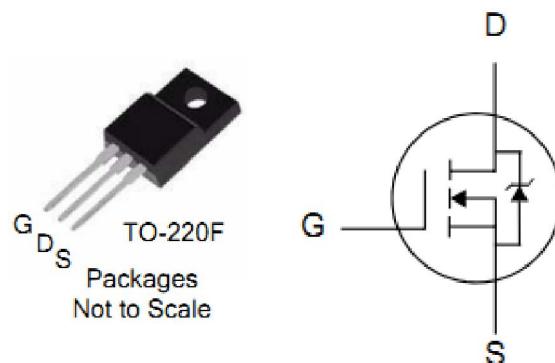
V_{DSS}	$R_{DS(ON)}(\text{Typ.})$	I_D
650V	0.49Ω	16A

Features:

- RoHS Compliant
- Low ON Resistance
- Low Gate Charge
- Peak Current vs Pulse Width Curve
- Inductive Switching Curves

Ordering Information

PART NUMBER	PACKAGE	BRAND
ITA16N65A	TO-220F	IPS

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	ITA16N65A	Units
V_{DSS}	Drain-to-Source Voltage	650	V
I_D	Continuous Drain Current	16	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	11.5	A
I_{DM}	Pulsed Drain Current, $V_{GS} @ 10\text{V}$ (NOTE *1)	64	A
P_D	Power Dissipation	70	W
	Derating Factor above 25°C	0.56	W/ $^\circ\text{C}$
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulse Avalanche Energy(NOTE *2)	800	mJ
dv/dt	Peak Diode Recovery dv/dt (NOTE *3)	5	V/ns
T_L	Maximum Temperature for Soldering	300	
T_J and T_{STG}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$

Thermal Resistance

Symbol	Parameter	Typ.	Units	Test Conditions
$R_{\theta JC}$	Junction-to-Case	1.79	$^\circ\text{C}/\text{W}$	Water cooled heatsink, P_D adjusted for a peak junction temperature of $+150^\circ\text{C}$.
$R_{\theta JA}$	Junction-to-Ambient	100		1 cubic foot chamber, free air.

OFF Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	650	--	--	V	$\text{V}_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$\text{V}_{\text{DS}}=650\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$ $T_J=25^\circ\text{C}$
		--	--	100		$\text{V}_{\text{DS}}=520\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	--	--	+100	nA	$\text{V}_{\text{GS}}=+30\text{V}$
	Gate-to-Source Reverse Leakage	--	--	-100		$\text{V}_{\text{GS}}= -30\text{V}$

ON Characteristics $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$R_{\text{DS}(\text{ON})}$	Static Drain-to-Source On-Resistance	--	0.49	0.55	Ω	$\text{V}_{\text{GS}}=10\text{V}$, $I_D=8\text{A}$
$\text{V}_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	2	--	4	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $I_D=250\mu\text{A}$
g_{fs}	Forward Transconductance	--	15	--	S	$\text{V}_{\text{DS}}=15\text{V}$, $I_D=8\text{A}$
Pulse width $\leqslant 300\mu\text{s}$; duty cycle $\leqslant 2\%$						

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
C_{iss}	Input Capacitance	--	2450	--	pF	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$
C_{oss}	Output Capacitance	--	218	--		
C_{rss}	Reverse Transfer Capacitance	--	18.5	--		
Q_g	Total Gate Charge	--	54	--	nC	$I_D=16\text{A}$, $\text{V}_{\text{DD}}=325\text{V}$ $\text{V}_{\text{GS}}=10\text{V}$
Q_{gs}	Gate-to-Source Charge	--	10	--		
Q_{gd}	Gate-to-Drain ("Miller") Charge	--	21	--		

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$t_{\text{d}(\text{ON})}$	Turn-on Delay Time	--	30		ns	$\text{V}_{\text{DD}}=325\text{V}$, $I_D=16\text{A}$, $\text{V}_G=10\text{V}$ $R_G=25\Omega$
t_{rise}	Rise Time	--	70			
$t_{\text{d}(\text{OFF})}$	Turn-Off Delay Time	--	145			
t_{fall}	Fall Time	--	74			

Source-Drain Diode CharacteristicsT_c=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	--	--	16	A	T _c =25°C
I _{SM}	Maximum Pulsed Current (Body Diode)	--	--	64	A	
V _{SD}	Diode Forward Voltage	--	--	1.5	V	I _{SD} =16A, V _{GS} =0V
t _{rr}	Reverse Recovery Time	--	410	--	ns	I _F = I _S di/dt=100A/us
Q _{rr}	Reverse Recovery Charge	--	3.5	--	uC	
Pulse width ≤300μs; duty cycle ≤ 2%						

Notes:

- *1. Repetitive rating; pulse width limited by maximum junction temperature.
- *2. L=10mH, I_D=12.6A, Start T_J=25°C
- *3. I_{SD}=16A, di/dt ≤100A/us, V_{DD}≤BV_{DS}, Start T_J=25°C

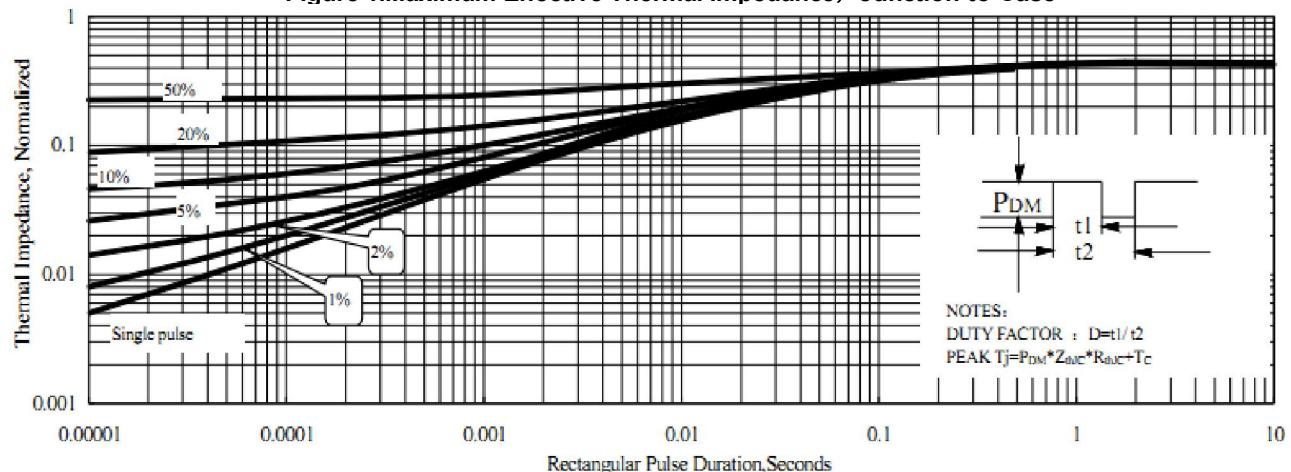
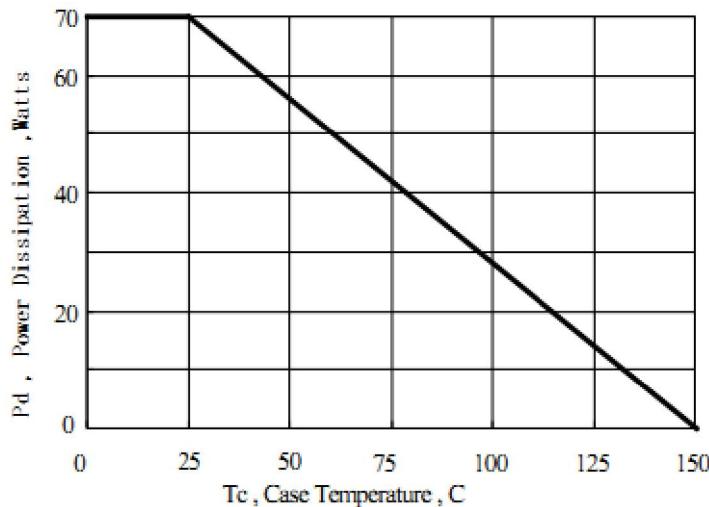
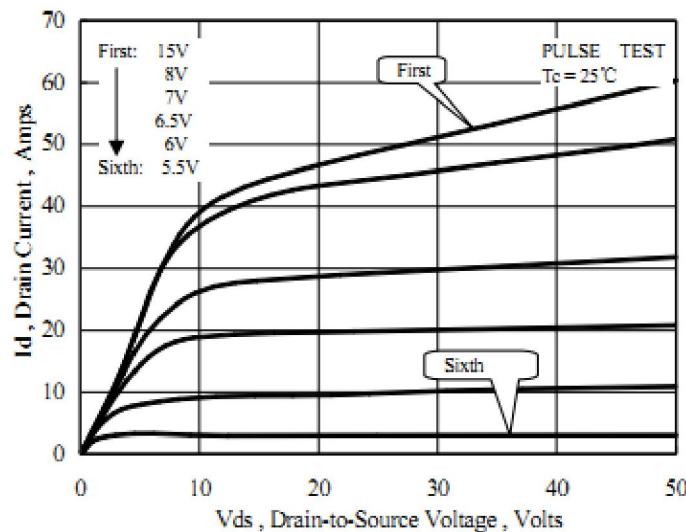
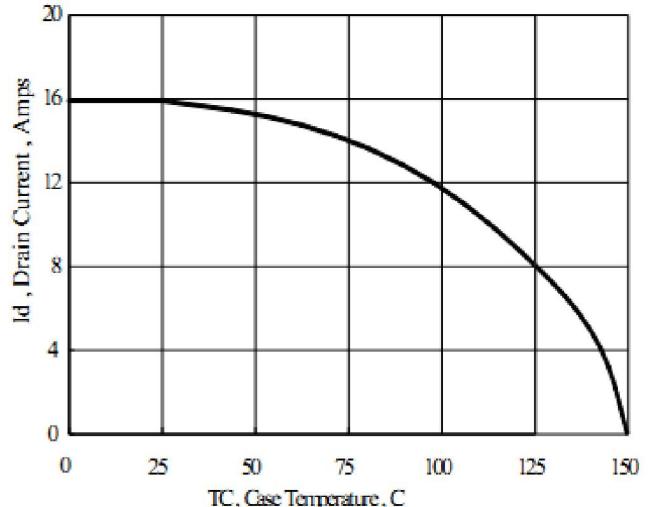
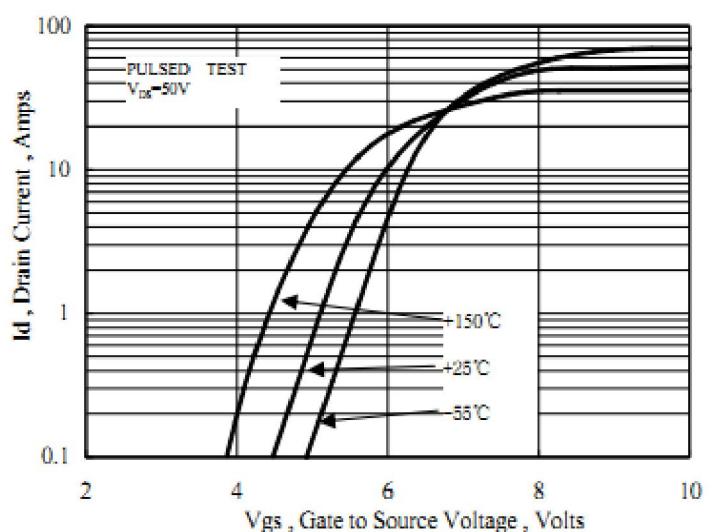
Characteristics Curve:
Figure 1. Maximum Effective Thermal Impedance, Junction-to-Case

Figure 2. Max. Power Dissipation vs Case Temperature

Figure 4. Typical Output Characteristics

Figure 3. Max. Drain Current vs Case Temperature

Figure 5. Typical Transfer Characteristics


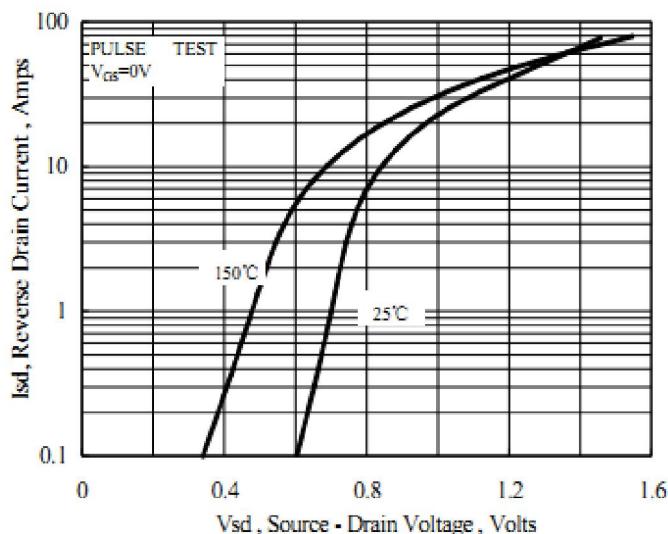
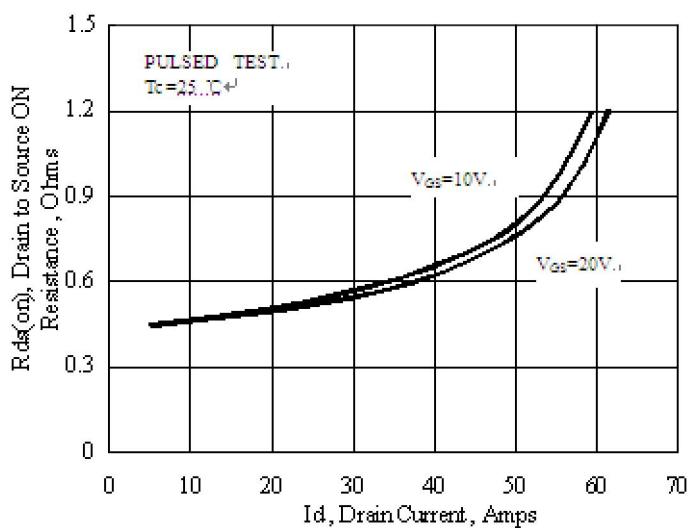
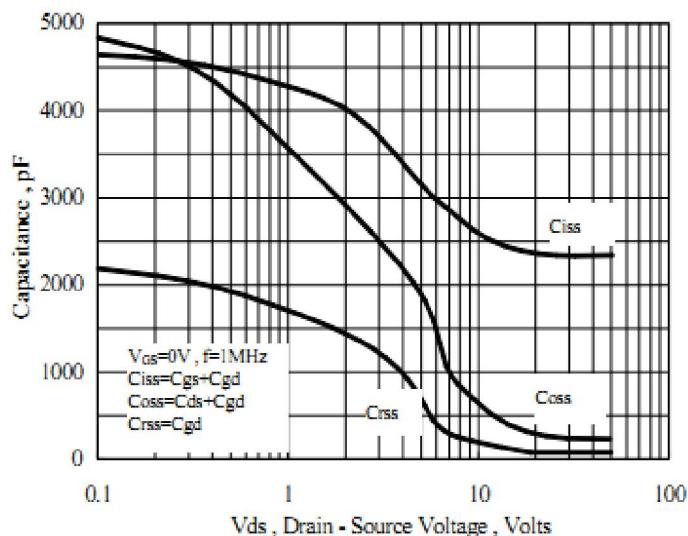
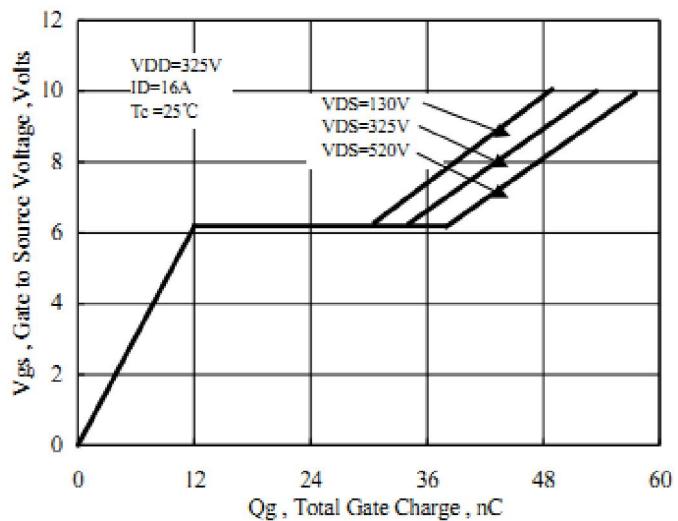
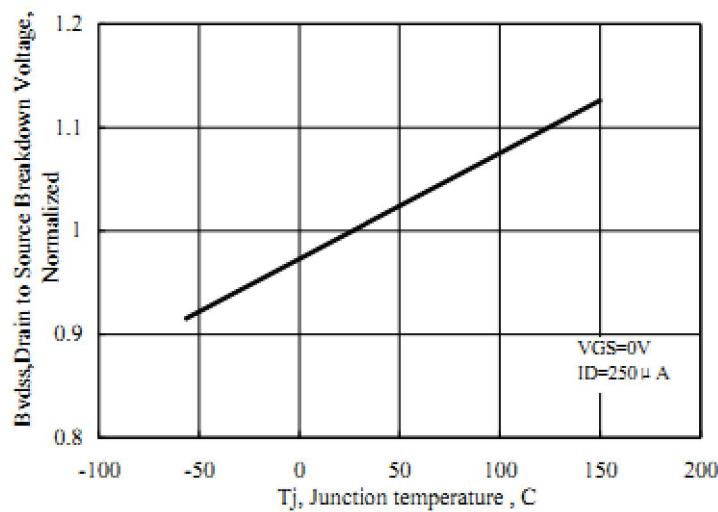
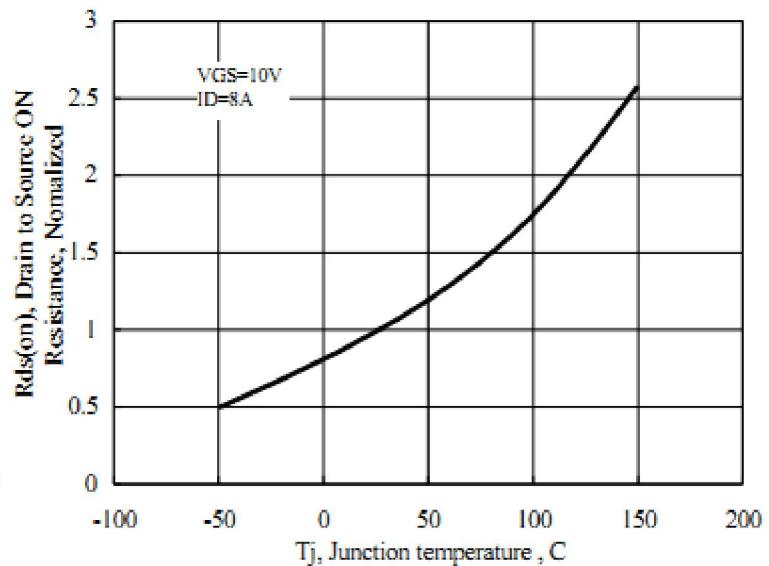
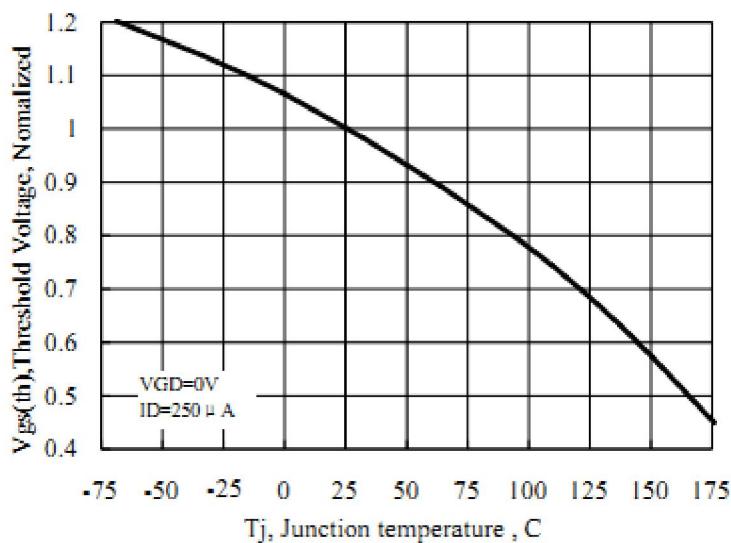
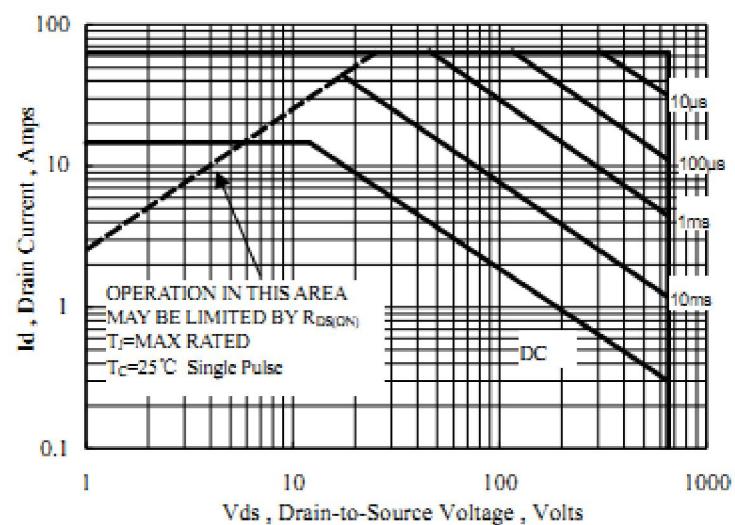
Figure 6. Typical Body Diode Transfer Characteristics

Figure 7. Typical on Resistance VS Drain Current

Figure 8. Capacitance VS Drain-to-Source Voltage

Figure 9. Gate Charge VS Gate-to-Source Voltage


Figure 10. Breakdown Voltage VS Temperature

Figure 11. on-Resistance VS Temperature

Figure 12 Threshold Voltage vs Junction Temperature

Figure 13. Safe Operating Area


Test Circuits and Waveforms

Figure 14. Gate Charge Test Circuit

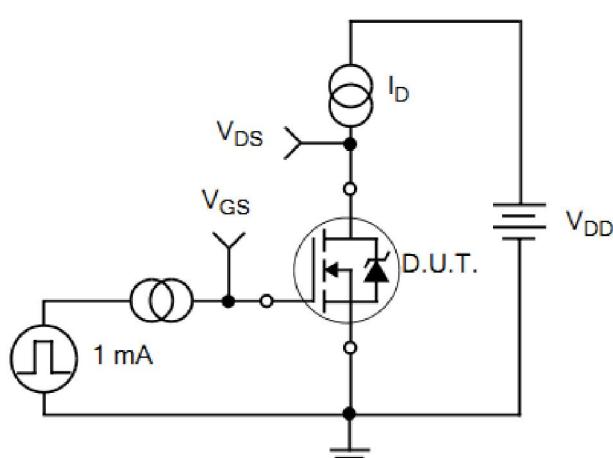


Figure 15. Gate Charge Waveforms

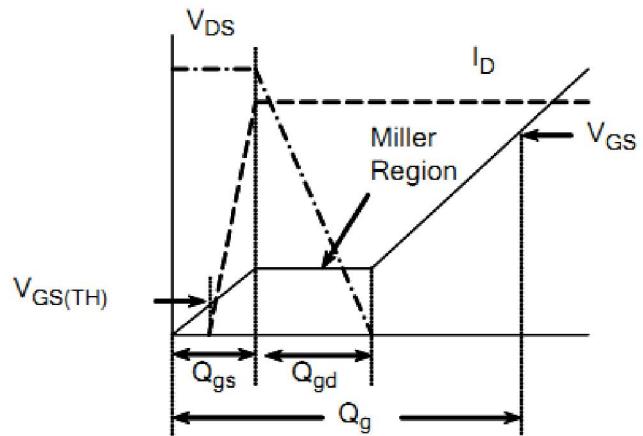


Figure 16. Resistive Switching Test Circuit

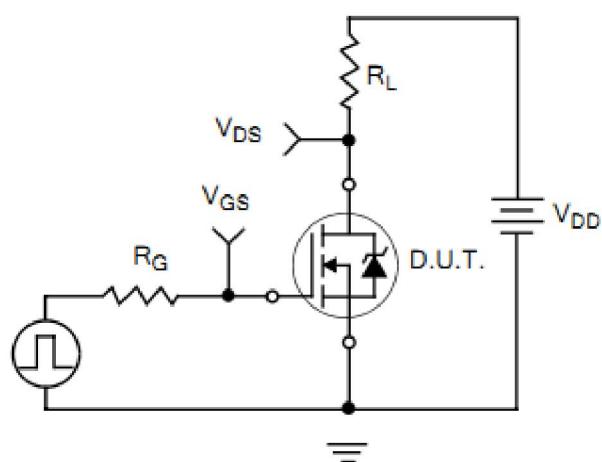


Figure 17. Resistive Switching Waveforms

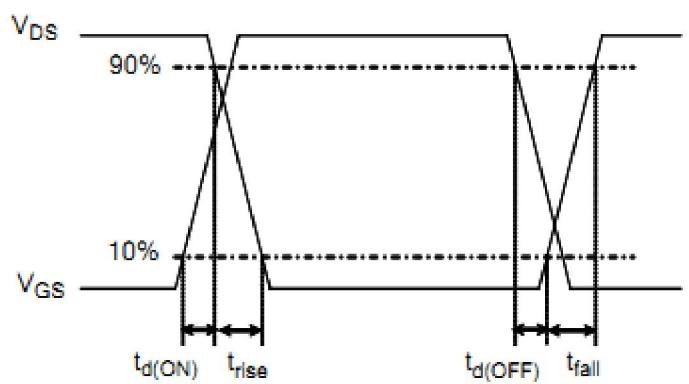


Figure 18. Diode Reverse Recovery Test Circuit

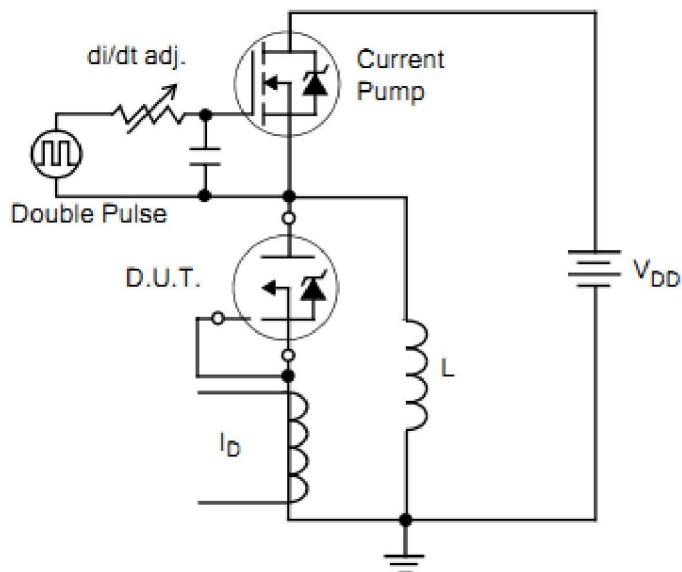


Figure 19. Diode Reverse Recovery Waveform

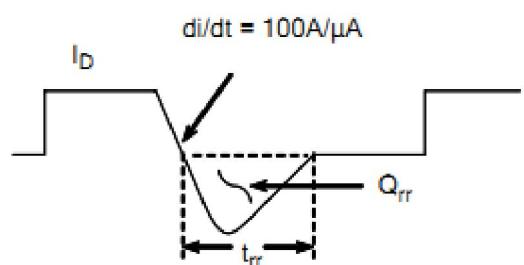


Figure20.Unclamped Inductive Switching Test Circuit

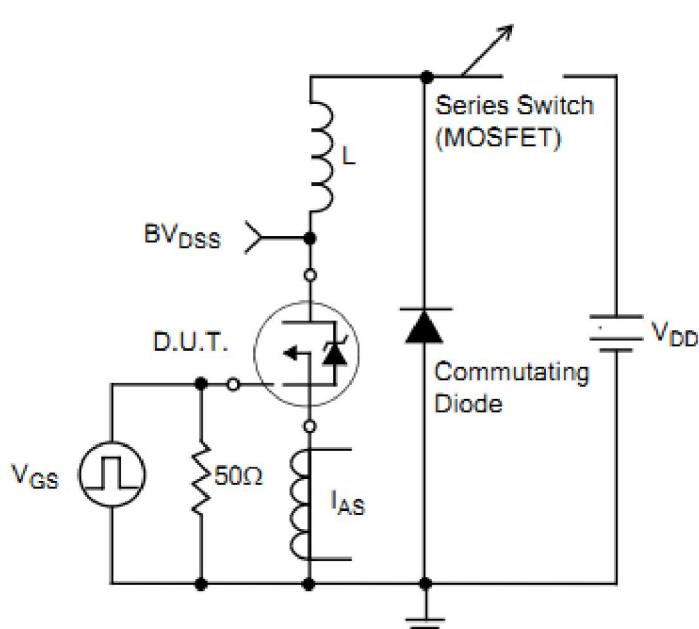
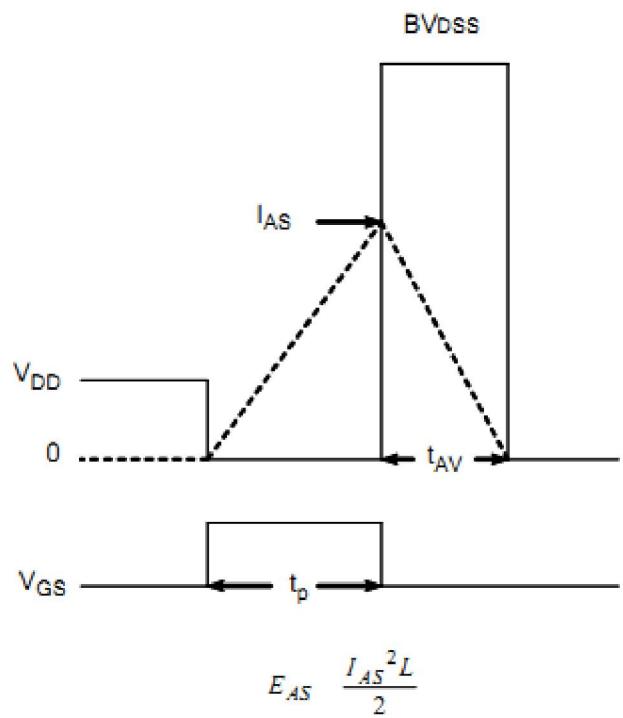


Figure21.Unclamped Inductive Switching Waveform



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